#### 507811470 03/21/2023

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
SIERRA CIRCUITS, INC.	07/16/2018

# **RECEIVING PARTY DATA**

Name: CATLAM LLC			
Street Address: 1108 W. EVELYN AVE.			
City: SUNNYVALE			
State/Country: CALIFORNIA			
Postal Code:	94086		

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17076342

### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	CER-2053-C1_SIER_TO_CAT		
NAME OF SUBMITTER:	JAY A. CHESAVAGE		
SIGNATURE:	/Jay A. Chesavage/		
DATE SIGNED:	03/21/2023		

#### **Total Attachments: 4**

source=2053-C1 sierra to catlam assn executed p#page1.tif source=2053-C1\_sierra\_to\_catlam\_assn\_executed\_p#page2.tif source=2053-C1\_sierra\_to\_catlam\_assn\_executed\_p#page3.tif source=2053-C1 sierra to catlam assn executed p#page4.tif

PATENT REEL: 063052 FRAME: 0990 507811470

# PATENT ASSIGNMENT

This Patent Assignment ("<u>Assignment</u>"), dated as of July 16, 2018 (the "<u>Effective Date</u>"), is entered into by and between Sierra Circuits, Inc ("Sierra"), a corporation of California, and Catlam LLC ("<u>Catlam</u>"), a limited liability company organized in Delaware. "Sierra" and "Catlam" may hereinafter be referred to collectively as the "<u>Parties</u>" or individually as a "<u>Party</u>."

# **RECITALS**

WHEREAS, "Sierra" is the owner of record of all right, title and interest in and to the following trademark and trademark application (the "Trademarks") listed on EXHIBIT A, and patents and patent applications (the "Patents") listed on EXHIBIT B, and;

WHEREAS, for valuable consideration, and effective July 16, 2018, the Parties wish hereby to provide for the transfer of ownership of the Trademarks and Patents from "Sierra" to "Catlam",

**NOW THEREFORE**, for good and valuable consideration of US \$1.00 (United States One Dollar), the receipt and sufficiency of which is hereby acknowledged, the Parties hereby agree as follows:

"Sierra" hereby assigns, grants and conveys to "Catlam" all of the "Sierra" right, title and interest in and to said Trademarks and to Patents and each of them, and in and to all patent reissues, divisions, continuations, renewals, extensions and continuations-in-part thereof, international patents, patent applications (including national phase applications filed pursuant to any PCT Applications referenced in Exhibit B), trademarks, and trademark applications filed thereof, and all rights of "Sierra" associated therewith, including the right to sue for any past infringement.

**IN WITNESS WHEREOF**, the Parties hereto have executed and delivered this Trademark and Patent Assignment as of the date first hereinabove written.

# Exhibit A

Trademark Applications

I J						
Trademark serial no						
		CATLAM word mark				

Assignment from "Sierra" to "Catlam"

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ASSIGNOR: Sierra Circuits, INC.  By: Supplied by: (Signature)
Name: Swaran Bala Balal
Title: Co-Owner  Address: 1108 W. Evelyn Ave, Sunnyvale, CA,US 94086
ASSIGNEE: Catlam, LLC
By: Kenneths Ball (Signature)
Name: Kenneth S. Bahl
Title: President

Address: 1108 W. Evelyn Ave, Sunnyvale, CA,US 94086

Exhibit B (Patents and Patent Applications)								
\	Issued							
Darlina								
Docket		Filing		Patent	Issue	i		
Number	Application Number	Date	Status	Number	Date	Title	Туре	
2039	14/281,802	5/19/14	Issued	9,398,703	7/19/16	VIA IN A PRINTED CIRCUIT BOARD	Utility: Non-Provisional	
2039-C2	15/184,426	6/16/16	Issued	9,674,967		VIA IN A PRINTED CIRCUIT BOARD	Utility: Non-Provisional	
2039-CIP	15/001,140	1/19/16	Issued	9,706,667		VIA IN A PRINTED CIRCUIT BOARD	Utility: Non-Provisional	
2039-CN	2015800/266,489	11/18/16		, , , , , ,	7.=-6.=-	Via in a Printed Circuit Board	Utility: Foreign	
2039-EPO	15708363.5/3146812		Published			Via in a Printed Circuit Board	Utility: Foreign	
2039-IN	201617/041,954		Published	1	<del>                                     </del>	Via in a Printed Circuit Board	Utility: Foreign	
2039-JP	2017-514256	11/18/16	<del></del>	<del>                                     </del>		VIA IN A PRINTED CIRCUIT BOARD	<del></del>	
2039-KR	10-2016-7034800		Published		-		Utility: Foreign	
2039-PCT	PCT/US15/14615		Published			VIA IN A PRINTED CIRCUIT BOARD	Utility: Foreign	
2039-FC1 2039-TW					· · · · · · · · · · · · · · · · · · ·	VIA IN A PRINTED CIRCUIT BOARD	Utility: PCT	
	104/115,823		Pending			Via in a Printed Circuit Board	Utility: Foreign	
2039-VN	201/604,569	11/25/16	Pending	<del></del>		VIA IN A PRINTED CIRCUIT BOARD	Utility: Foreign	
						METHOD FOR FORMING TRACES OF		
2044	14/281,631	5/19/14	Issued	9,380,700	6/28/16	A PRINTED CIRCUIT BOARD	Utility: Non-Provisional	
						WAFER LEVEL PACKAGING USING A		
2044-C2	15/009,386		Published			CATALYTIC ADHESIVE	Utility: Non-Provisional	
2044-C3	15/165,458	<del></del>	Published			PRINTED CIRCUIT BOARD	Utility: Non-Provisional	
2044-CN	2015800/266,440	11/18/16	Pending			Embedded Traces	Utility: Foreign	
2044-EPO	EP15709567.0/3146809	2/5/15	Published			Embedded Traces	Utility: Foreign	
2044-IN	201617041953.00	12/8/16	Published			Embedded Traces	Utility: Foreign	
2044-JP	2017/514,255	11/18/16	Pending			Embedded Traces	Utility: Foreign	
20/44-KR	10-2016-7034801	12/12/16	Published		787	Embedded Traces	Utility: Foreign	
2044-PCT	PCT/US15/14599	2/5/15	Published			EMBEDDED TRACES	Utility: PCT	
2044-TW	104/115,821	5/19/15	Pending			Embedded Traces	Utility: Foreign	
2044-VN	1201/604,570	11/25/16	<del></del> _			Embedded Traces		
	1	11/25/10	rending	<del> </del>			Utility: Foreign	
2044C	14/297,516	6/5/14	lecued	9,631,279	4/25/47	METHODS FOR FORMING		
2044C-CN	2015800/266722	11/18/16		3,031,279	4/25/17	EMBEDDED TRACES	Utility: Non-Provisional	
2044C-EPO	15709568.8/3146810			ļ	-	Embedded Traces	Utility: Foreign	
2044C-IN	201617/041,723		Published	<del> </del>		Embedded Traces	Utility: Foreign	
2044C-JP	<del></del>		Published			Embedded Traces	Utility: Foreign	
2044C-JP 2044C-KR	2017/514,257	11/18/16				Embedded Traces	Utility: Foreign	
	10-2016-7034802		Published		<del></del>	Embedded Traces	Utility: Foreign	
2044C-PCT	PCT/US15/14619		Published			EMBEDDED TRACES	Utility: PCT	
2044C-TW	104/115,822	5/19/15				Embedded Traces	Utility: Foreign	
2044C-VN	1201/604,571	11/25/16	Pending			Embedded Traces	Utility: Foreign	
						CATALYTIC LAMINATE APPARATUS		
2050	15/240,133	8/18/16	Issued	9,706,650	7/11/17	AND METHOD	Utility: Non-Provisional	
						PLASMA ETCHED CATALYTIC	7	
2050/2053-PCT	PCT/US17/47062	8/16/17	Published			LAMINATE WITH TRACES AND VIAS	Utility: PCT	
							o and just of	
2050_C1	15/603,326	5/23/17	Allowed			Circuit Board Apparatus and Method	Utility: Non-Provisional	
						enedic board Apparatus and Method	Othity. Non-Provisional	
2050-C2	15/878,398	1/23/18	Pending			Circuit board with Catalytic Adhesive	I Itilituu Alam Duardataaal	
							Othicy: Non-Provisional	
2051	15/350,019	11/12/16	Allowed			Integrated Circuit Wafer Integration	I tariffy by D	
	15/050/025	11/12/10	Allowed			with Catalytic Laminate or Adhesive	Utility: Non-Provisional	
		ĺ				Method and Apparatus for forming		
2051-C1	15/889,017	2/5/10	Pending			Contacts on an Integrated Circuit Die		
2031 CI	15/665,017	2/3/10	Pending			using a Catalytic Adhesive	Utility: Non-Provisional	
						INTEGRATED CIRCUIT WAFER		
20E1 DCT	DCT/UC17/C1100	44/40/47				INTEGRATION WITH CATALYTIC		
2051-PCT	PCT/US17/61109	11/10/17	rublished			LAMINATE OR ADHESIVE	Utility: PCT	
20E1 TW	100/120 012	44/				Integrated Circuit Wafer Integration		
2051-TW	106/139,012	11/10/17	Pending				Utility: Foreign	
					1	Multi-Layer Circuit Board using		
						Interposer layer and Conductive		
2052	15/635,201	6/28/17	Pending			Paste	Utility: Non-Provisional	
						Multi-Layer Circuit Board using	, , , , , , , , , , , , , , , , , , , ,	
		1		1				
		1		1	l l	Interposer layer and Conductive	1	

2052-T <b>W</b>	107/122,327	6/28/18	Pending	Multi-Layer Circuit Board using Interposer layer and Conductive Paste	Utility: Foreign
2053-C1 2053	17/076,342 15/645,957	10/21/20 7/10/17	Pending	Plasma Etched Catalytic Laminate with Traces and Vias	Utility: Non-Provisional
2054	15/645,921	7/10/17	Pending	Semi-additive process for printed circuit boards	Utility: Non-Provisional
2054-PCT	PCT/US18/41293	7/9/18	Pending	SEMI-ADDITIVE PROCESS FOR PRINTED CIRCUIT BOARDS	Utility: PCT
2055	15/911,515	3/5/18	Pending	Catalytic Laminate with Conductive Traces formed during Lamination	Utility: Non-Provisional
2057	16/024,835	6/30/18	Pending	UV curable Catalytic Adhesive for Circuit Boards with Traces and Vias	Utility: Non-Provisional

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PATENT

REEL: 063052 FRAME: 0994